

09/25/1988

ABSTRACT

STRUCTURAL DESIGN AND PROCESSES TO
CONTROL PROBE POSITION ACCURACY IN A WAFER TEST PROBE ASSEMBLY

The present invention is directed to a structure comprising a substrate having a surface; a plurality of elongated electrical conductors extending away from the surface; each of said elongated electrical conductors having a first end affixed to the surface and a second end projecting away from the surface; there being a plurality of second ends; and a means for positioning and maintaining the plurality of the second ends in substantially fixed positions with respect to each other. The structure is useful as a probe for testing and burning in integrated circuit chips at the wafer level.

09251988-021799